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2007-07

**Surface mounting technology –
Environmental and endurance test
methods for surface mount solder joint –**

**Part 1-1:
Pull strength test**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SURFACE MOUNTING TECHNOLOGY –
ENVIRONMENTAL AND ENDURANCE TEST METHODS
FOR SURFACE MOUNT SOLDER JOINT –**

Part 1-1: Pull strength test

FOREWORD

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The text of this standard is based on the following documents:

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Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all the parts in the IEC 62137 series, under the general title *Surface mounting technology – Environmental and endurance test methods for surface mount solder joint*, can be found on the IEC website.

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